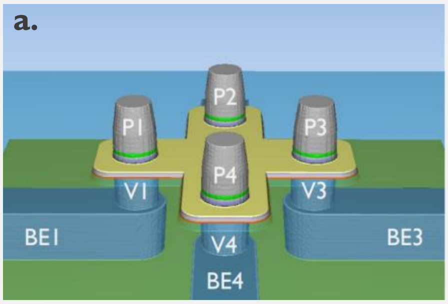
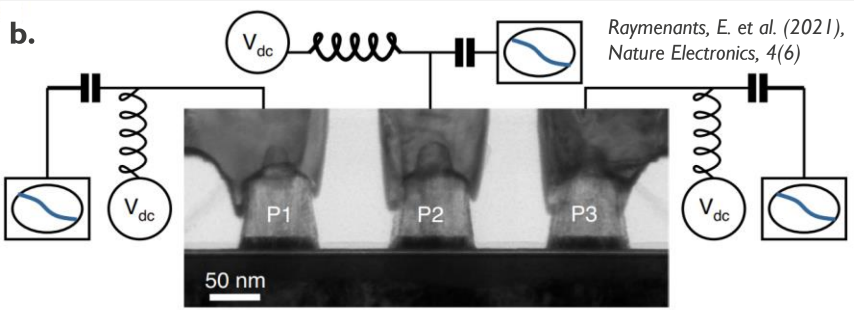
AVS 68 abstract - Illustrations





Raymenants, E. et al. (2021), Nature Electronics, 4(6)

Figure 1.a. : *Cross-shape magnetic interconnect design. 3 input MTJ pillars + 1 output MTJ pillar interconnected by a magnetic track (in yellow).*
Figure 1.b. : *Cross-section TEM view of the spin logic architecture.*

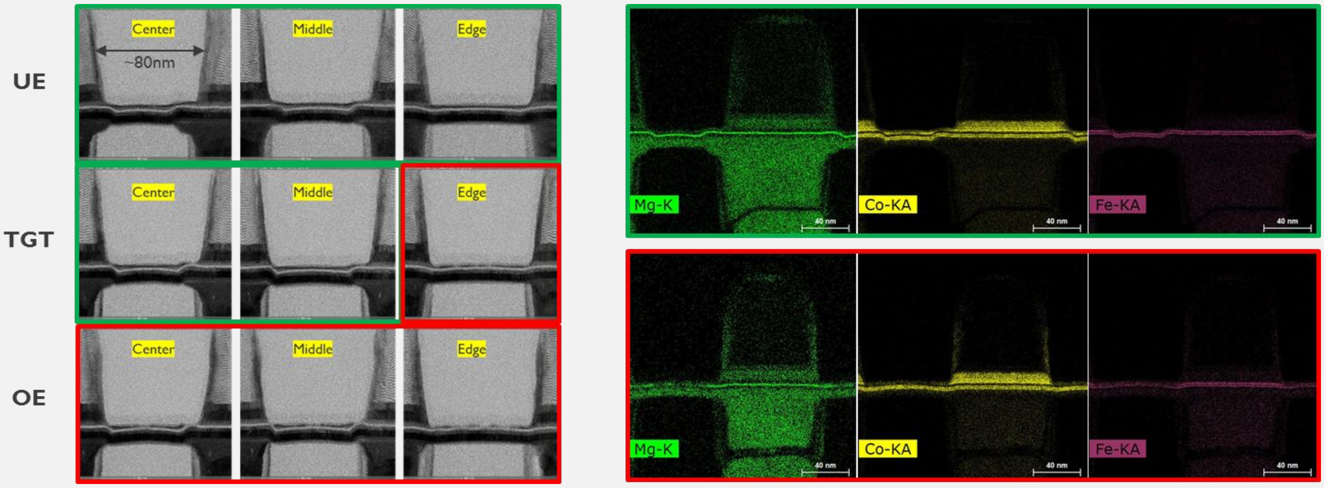


Figure 2 : *TEM-EDS analysis after MTJ pillar etch as function of the etch stop conditions.*
UE = "Underetch" ; TGT = "Target" ; OE = "Overetch"

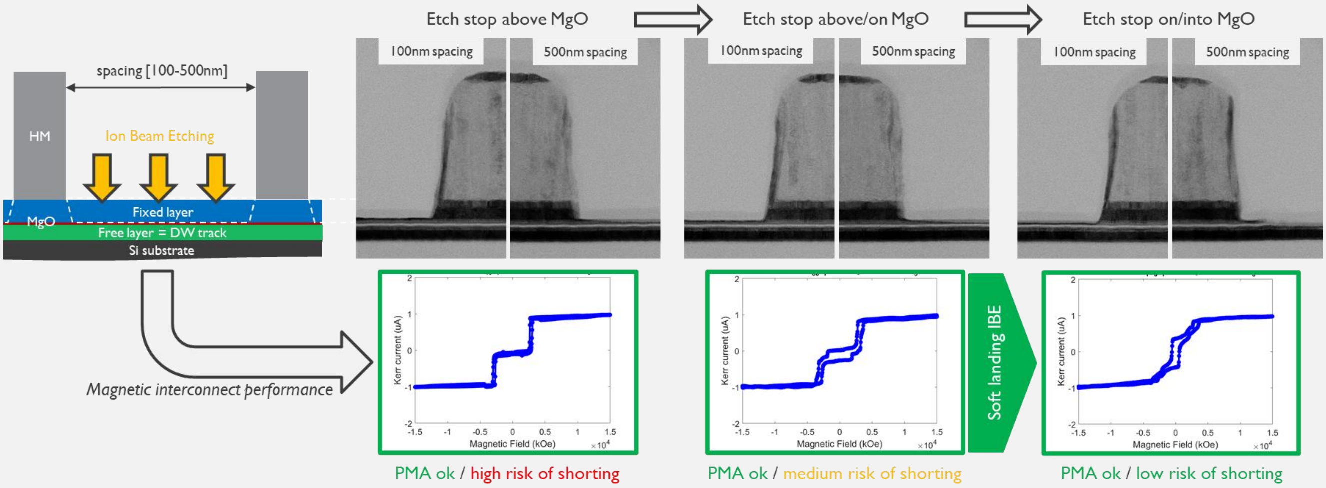


Figure 3 : *Magnetic behavior of the Domain Wall (DW) track as function of the etch conditions.*